

	<h1>Tentative</h1>	<b>DMC364A6</b>	
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## DMC364A6

Silicon NPN epitaxial planar type (Tr1)

Silicon NPN epitaxial planar type (Tr2)

For digital circuits

Marking Symbol : N2

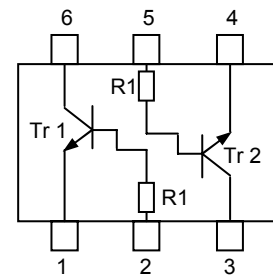
Package Code : SSSMini6-F2-B

### Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

	Parameter	Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	VCBO	50	V
	Collector-emitter voltage (Base open)	VCEO	50	V
Tr2	Collector current	IC	80	mA
Overall	Total power dissipation *1	PT	125	mW
	Junction temperature	Tj	150	$^\circ\text{C}$
	Storage temperature	Tstg	-55 to +150	$^\circ\text{C}$

Note: 1. \*1 Measuring on substrate at 17 mm × 10 mm × 1 mm

### Internal Connection



Resistance value	R1	4.7	k $\Omega$
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### Pin name

1. Emitter(Tr1)	4. Emitter(Tr2)
2. Base(Tr1)	5. Base(Tr2)
3. Collector(Tr2)	6. Collector(Tr1)

### Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Tr1,Tr2		Parameter	Symbol	Conditions	Min	Typ	Max	Unit
		Collector-base voltage (Emitter open)	VCBO	IC = 10 $\mu\text{A}$ , IE = 0	50			V
		Collector-emitter voltage (Base open) *1	VCEO	IC = 2 mA, IB = 0	50			V
		Collector-base cutoff current (Emitter open)	ICBO	VCB = 50 V, IE = 0			0.1	$\mu\text{A}$
		Collector-emitter cutoff current (Base open)	ICEO	VCE = 50 V, IB = 0			0.5	$\mu\text{A}$
		Emitter-base cutoff current (Collector open)	IEBO	VEB = 6 V, IC = 0			0.01	mA
		Forward current transfer ratio	hFE	VCE = 10 V, IC = 5 mA	160		460	-
		Collector-emitter saturation voltage	VCE(sat)	IC = 10 mA, IB = 0.5 mA			0.25	V
		Input voltage	Vi(on)	VCE = 0.2 V, IC = 5 mA	1.0			V
			Vi(off)	VCE = 5 V, IC = 100 $\mu\text{A}$			0.4	
		Input resistance	R1		-30%	4.7	+30%	k $\Omega$

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. \*1 Pulse measurement

### Packing

Embossed type (Thermo-compression sealing) R specification : 10 000 pcs / reel

2010.3.11	2010.11.25	
Prepared	Revised	

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